


# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/25/15422
1.3 Title of PCN	ASE KaoHsiung (Taiwan) additional source for STM32F74/75xx, STM32F76/77xx listed products in TFBGA 13X13 216L package and STM32F20/21xx, STM32F40/41xx, STM32F42/43xx listed products in UFBGA 10X10 176+25 package.
1.4 Product Category	STM32F74/75xx, STM32F76/77xx, STM32F20/21xx, STM32F40/41xx and STM32F42/43xx
1.5 Issue date	2025-09-16

## 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

## 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE KaoHsiung (Taiwan)

## 4. Description of change

	Old	New
4.1 Description	<p>Current assembly sites (depending on package/product):</p> <ul style="list-style-type: none"> <li>- AMKOR ATP (Philippine) Gold for Crolles, TSMC &amp; Rousset Dice,</li> <li>- AMKOR ATP (Philippine) Copper Palladium wire for Crolles, TSMC Dice,</li> <li>- ASE Kaohsiung (Taiwan) Gold wire for Crolles, TSMC &amp; Rousset Dice,</li> <li>- ASE Kaohsiung (Taiwan) Copper Palladium wire for Crolles &amp; TSMC Dice,</li> </ul> <p>You may refer to 15422_Additional information.pdf document for further details.</p>	<p>Current assembly sites: (depending on package/product):</p> <ul style="list-style-type: none"> <li>- AMKOR ATP (Philippine) Gold for Crolles, TSMC &amp; Rousset Dice,</li> <li>- AMKOR ATP (Philippine) Copper Palladium wire for Crolles, TSMC Dice,</li> <li>- ASE Kaohsiung (Taiwan) Gold wire for Crolles, TSMC &amp; Rousset Dice,</li> <li>- ASE Kaohsiung (Taiwan) Copper Palladium wire for Crolles &amp; TSMC Dice,</li> </ul> <p>Additional assembly site for extended capacity:</p> <ul style="list-style-type: none"> <li>- ASE Kaohsiung (Taiwan) Copper Palladium wire for Rousset Dice.</li> </ul>
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact on Form, Fit or Function	

## 5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

## 6. Marking of parts / traceability of change

6.1 Description	Change is visible in the marking. Please refer to PCN 15422_Additional information.pdf document for further details.
-----------------	---

## 7. Timing / schedule

7.1 Date of qualification results	2025-10-07
7.2 Intended start of delivery	2025-11-07

7.3 Qualification sample available?	Upon Request
-------------------------------------	--------------

8. Qualification / Validation			
8.1 Description	15422 MDRF-GPAM-RER2520 PCN15422- ASEKH TFBGA216L and UFBGA176+25- Reliability Plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2025-09-16

9. Attachments (additional documentations)	
15422 Public product.pdf 15422 MDRF-GPAM-RER2520 PCN15422- ASEKH TFBGA216L and UFBGA176+25- Reliability Plan.pdf 15422 _Additional information.pdf	

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F407IGH6	
	STM32F746NGH6	
	STM32F769NIH6	

## **IMPORTANT NOTICE – PLEASE READ CAREFULLY**

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved